APPARATUS AND METHOD FOR PROCESSING A SUBSTRATE

ABSTRACT OF THE DISCLOSURE

A method for processing a substrate is provided which includes applying fluid onto a surface of the substrate from a portion of a plurality of inlets and removing at least the fluid from the surface of the substrate where the removing being processed as the fluid is applied to the surface. The applying the fluid and the removing the fluid forms a segment of a fluid meniscus on the surface of the substrate.

(Figure 2)